



Product Change Notification / ALAN-11ELYX284

Date:

08-Dec-2022

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4768 Final Notice: Qualification of ANAP as an additional assembly site for selected Atmel ATSAMG55J19A and ATSAMG55J19B device families available in 64L LQFP (10x10x1.4mm) package.

Affected CPNs:

[ALAN-11ELYX284_Affected_CPN_12082022.pdf](#)
[ALAN-11ELYX284_Affected_CPN_12082022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ANAP as an additional assembly site for selected Atmel ATSAMG55J19A and ATSAMG55J19B device families available in 64L LQFP (10x10x1.4mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
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Assembly location	ASE Inc. (ASE)	ASE Inc. (ASE)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Bond wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	CRM-1076WA	CRM-1076WA	3230
Mold compound material	G631H	G631H	G631HQ
Lead-frame	Material	C7025	C7025
	See pre and post change comparison		

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change: To improve productivity by qualifying ANAP as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: January 31, 2022 (date code: 2206)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Issue Date														
Estimated Implementation Date								X						

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:July 27, 2021: Issued initial notification.

August 31, 2021: Re-issued initial notification to update the mold compound material from G700Y to G631HQ for ANAP assembly site in PCN letter and Qual plan. Updated the Pre and Post change file to reflect the lead frame information only for ASE and ANAP.

January 6, 2022: Issued final notification. Updated the estimated qualification completion date to be on May 13, 2022. Provided the estimated first ship date to be on January 31, 2022.

December 8, 2022: Re-issued final notification to attach the Qualification Report. Updated the time table summary to reflect qual report availability.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_ALAN-11ELYX284_Qual Report.pdf](#)

[PCN_ALAN-11ELYX284 - Pre and Post Change_Summary.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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